TOSHIBA Photocoupler GaAs Ired & Photo-Thyristor

# **TLP741G**

Office Machine
Household Use Equipment
Solid State Relay
Switching Power Supply

The TOSHIBA TLP741G consists of a photo-thyristor optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

- Peak off-state voltage: 400V(min.)
- Trigger LED current: 10mA(max.)
- On-state current: 150mA(max.)
- UL recognized: UL1577, file no. E67349
- BSI approved: BS EN60065: 2002

Certificate no. 8877 BS EN60950-1: 2002 Certificate no. 8878

- Isolation voltage: 4000V<sub>rms</sub>(min.)
- Option (D4) type

VDE approved: DIN EN 60747-5-2

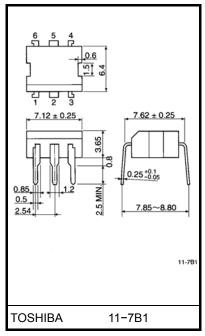
Certificate no. 40009302

Maximum operating insulation voltage:  $630 V_{PK}$  Highest permissible over voltage:  $6000 V_{PK}$ 

# (Note) When a EN 60747-5-2 approved type is needed, please designate the "option (D4)"

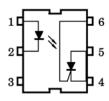
	7.62mm pich standard type	10.16mm pich (LF2) type
• Creepage distance:	7.0mm(min.)	8.0mm(min.)
Clearance:	7.0mm(min.)	8.0mm(min.)
Insulation thickness:	0.5mm(min.)	0.5mm(min.)

Unit in mm



Weight: 0.35 g (typ.)

### Pin Configuration (top view)



1 : ANODE 2 : CATHODE

3: NC

4 : CATHODE 5 : ANODE

6: GATE

#### Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit
LED	Forward current	l <sub>F</sub>	60	mA
	Forward current derating (Ta ≥ 39°C)	ΔI <sub>F</sub> / °C	-0.7	mA / °C
	Peak forward current (100µs pulse, 100pps)	I <sub>FP</sub>	1	Α
	Power dissipation	P <sub>D</sub>	100	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP <sub>D</sub> / °C	-1.0	mW / °C
	Reverse voltage	V <sub>R</sub>	5	V
	Junction temperature	Tj	125	°C
	Peak forward voltage( $R_{GK} = 27k\Omega$ )	$V_{DRM}$	400	V
	Peak reverse voltage(R <sub>GK</sub> = 27kΩ)	$V_{RRM}$	400	V
	On-state current	I <sub>T(RMS)</sub>	150	mA
	On–state current derating (Ta ≥ 25°C)	ΔI <sub>T</sub> / °C	-2.0	mA / °C
ctor	Peak on-state current (100µs pulse, 120pps)	I <sub>TP</sub>	3	Α
Detector	Peak one cycle surge current	I <sub>TSM</sub>	2	Α
	Peak reverse gate voltage	$V_{GM}$	5	V
	Power dissipation	P <sub>D</sub>	150	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP <sub>D</sub> / °C	-2.0	mW / °C
	Junction temperature	Tj	100	°C
Storage temperature range		T <sub>stg</sub>	-55~125	°C
Operating temperature range		T <sub>opr</sub>	-55~100	°C
Lead soldering temperature (10s)		T <sub>sol</sub>	260	°C
Total p	package power dissipation	P <sub>T</sub>	250	mW
Total package power dissipation derating (Ta ≥ 25°C)		ΔP <sub>T</sub> / °C	-3.3	mW / °C
Isolatio	on voltage (AC, 1 min., R.H. ≤ 60%)	BVS	4000	V <sub>rms</sub>

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

### **Recommended Operating Conditions**

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V <sub>AC</sub>	_	_	120	V <sub>ac</sub>
Forward current	l <sub>F</sub>	15	20	25	mA
Operating temperature	T <sub>opr</sub>	-25	_	85	°C
Gate to cathode resistance	R <sub>GK</sub>	_	27	33	kΩ
Gate to cathode capacity	C <sub>GK</sub>	_	0.01	0.1	μF

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

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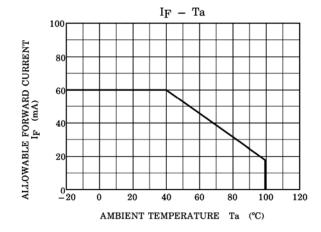
## Individual Electrical Characteristics (Ta = 25°C)

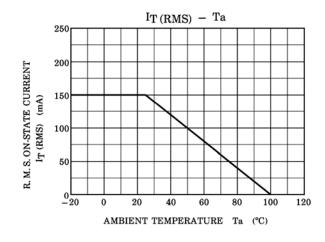
	Characteristic	Symbol	Test Condition		Min.	Тур.	Max.	Unit
	Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 10mA		1.0	1.15	1.3	V
LED	Reverse current	1 1 1			_	_	10	μΑ
	Capacitance				_	30	_	pF
Detector	Off-state current	l==	V <sub>AK</sub> = 400V R <sub>GK</sub> = 27kΩ	Ta = 25°C	_	10	5000	nA
		I <sub>DRM</sub>		Ta = 100°C	_	1	100	μA
	Reverse current I <sub>RRI</sub>	l	V <sub>KA</sub> = 400V	Ta = 25°C	_	10	5000	nA
		IRRM	$R_{GK} = 27k\Omega$	Ta = 100°C	_	1	100	μA
	On-state voltage	V <sub>TM</sub>	I <sub>TM</sub> = 100mA		_	0.9	1.3	V
	Holding current	lн	R <sub>GK</sub> = 27kΩ		_	0.2	_	mA
	Off–state dv / dt	dv/dt	$V_D = 280V, R_{GK} = 27k\Omega$		5	10	_	V/µs
	Consistence	C.	V = 0, f = 1MHz	Anode to gate	_	20	_	nΕ
	Capacitance	e	v - 0, i = 11VIH2	Gate to cathode		350	_	pF

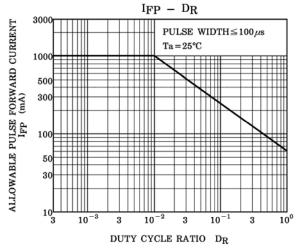
## Coupled Characteristics (Ta = 25°C)

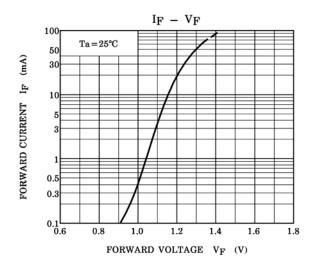
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
Trigger LED current	I <sub>FT</sub>	$V_{AK}$ = 6V, $R_{GK}$ = 27k $\Omega$	_	4	10	mA	
Turn-on time	ton	$I_{F} = 30 \text{mA}, V_{AA} = 50 \text{V},$ $R_{GK} = 27 \text{k}\Omega$		10	_	μs	
Coupled dv/dt	dv/dt	$V_S = 500V, R_{GK} = 27k\Omega$	500	_	_	V/µs	
Capacitance (input to output)	CS	V <sub>S</sub> = 0, f = 1MHz	_	0.8	-	pF	
Isolation resistance	R <sub>S</sub> V <sub>S</sub> = 500V		1×10 <sup>12</sup>	10 <sup>14</sup>	_	Ω	
	BVS	AC, 1 minute	4000	_	_	\/	
Isolation voltage		AC, 1 second, in oil	_	10000	_	V <sub>rms</sub>	
		DC, 1 minute, in oil	_	10000	_	V <sub>dc</sub>	

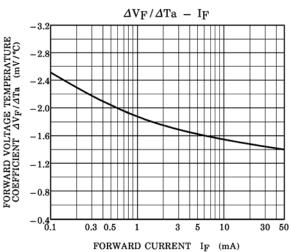
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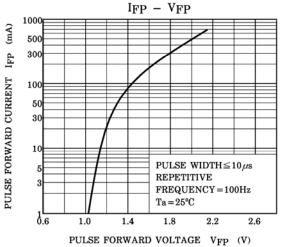


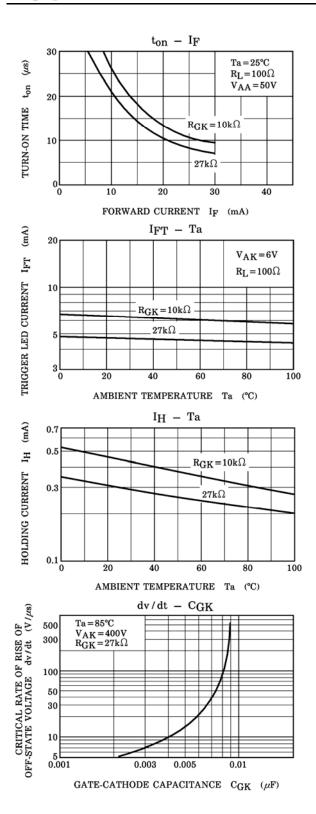


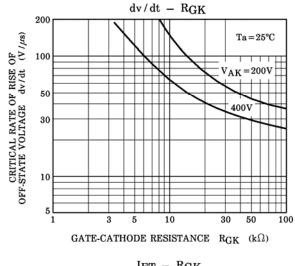


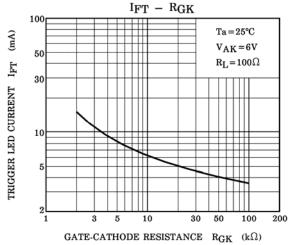


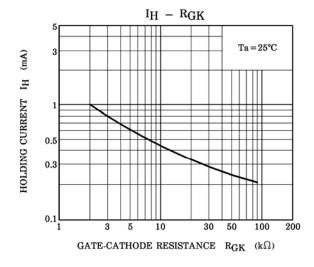












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